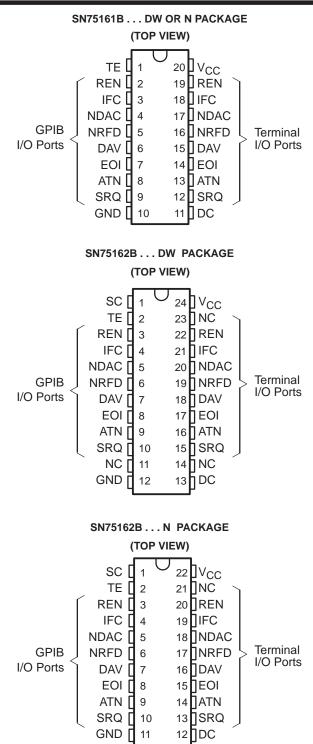
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- Meets IEEE Standard 488-1978 (GPIB)
- 8-Channel Bidirectional Transceivers
- Power-Up/Power-Down Protection (Glitch Free)
- Designed to Implement Control Bus Interface
- SN75161B Designed for Single Controller
- SN75162B Designed for Multiple Controllers
- High-Speed, Low-Power Schottky Circuitry
- Low Power Dissipation . . . 72 mW Max Per Channel
- Fast Propagation Times . . . 22 ns Max
- High-Impedance pnp Inputs
- Receiver Hysteresis . . . 650 mV Typ
- Bus-Terminating Resistors Provided on Driver Outputs
- No Loading of Bus When Device Is Powered Down (V_{CC} = 0)

description

The SN75161B and SN75162B eight-channel, general-purpose interface bus transceivers are monolithic, high-speed, low-power Schottky devices designed to meet the requirements of IEEE Standard 488-1978. Each transceiver is designed to provide the bus-management and data-transfer signals between operating units of a single- or multiple-controller instrumentation system. When combined with the SN75160B octal bus transceiver, the SN75161B or SN75162B provides the complete 16-wire interface for the IEEE-488 bus.

The SN75161B and SN75162B feature eight driver-receiver pairs connected in a front-to-back configuration to form input/output (I/O) ports at both the bus and terminal sides. A power-up/-down disable circuit is included on all bus and receiver outputs. This provides glitch-free operation during V_{CC} power up and power down.



NC-No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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description (continued)

The direction of data through these driver-receiver pairs is determined by the DC, TE, and SC (on SN75162B) enable signals. The SC input on the SN75162B allows the REN and IFC transceivers to be controlled independently.

The driver outputs (GPIB I/O ports) feature active bus-terminating resistor circuits designed to provide a high impedance to the bus when supply voltage V_{CC} is 0. The drivers are designed to handle loads up to 48 mA of sink current. Each receiver features pnp transistor inputs for high input impedance and hysteresis of 400 mV for increased noise immunity. All receivers have 3-state outputs to present a high impedance to the terminal when disabled.

The SN75161B and SN75162B are characterized for operation from 0°C to 70°C.

Function Tables

				01173101	B RECEIVE/					
	CONTROLS BUS-MANAGEMENT CHANNELS							DATA-TF	RANSFER CH	ANNELS
DC	TE	ATN [†]	ATN [†]	SRQ	REN	IFC	EOI	DAV	NDAC	NRFD
				(Controlle	ed by DC)		(Controlled by TE)			
Н	Н	Н	R	т	R	R	Т	т	R	R
Н	Н	L	ĸ	I	r.	IX.	R		ĸ	ĸ
L	L	Н	т	Р	т	Т	R	R	Т	т
L	L	L	I	R	I		Т			I
Н	L	Х	R	Т	R	R	R	R	Т	Т
L	Н	Х	Т	R	Т	Т	Т	Т	R	R

SN75161B RECEIVE/TRANSMIT

H = high level, L = low level, R = receive, T = transmit, X = irrelevant

Direction of data transmission is from the terminal side to the bus side, and the direction of data receiving is from the bus side to the terminal side. Data transfer is noninverting in both directions.

[†] ATN is a normal transceiver channel that functions additionally as an internal direction control or talk enable for EOI whenever the DC and TE inputs are in the same state. When DC and TE are in opposite states, the ATN channel functions as an independent transceiver only.

· · · · · ·												
	CONTROLS				BUS-MANAGEMENT CHANNELS					DATA-TRANSFER CHANNELS		
SC	DC	TE	ATN [†]	ATN [†]	SRQ	REN	IFC	EOI	DAV	NDAC	NRFD	
				(Controlle	ed by DC)	(Controlle	ed by SC)		(Co	ontrolled by	TE)	
	Н	Н	Н	R	т			Т	т	R	R	
	Н	Н	L	R I				R	1	IX		
	L	L	Н	т	R			R	R	т	т	
	L	L	L		ĸ			Т	1 ~	I	1	
	Н	L	Х	R	Т			R	R	Т	Т	
	L	Н	Х	Т	R			Т	Т	R	R	
Н						Т	Т					
L						R	R					

SN75162B RECEIVE/TRANSMIT

H = high level, L = low level, R = receive, T = transmit, X = irrelevant

Direction of data transmission is from the terminal side to the bus side, and the direction of data receiving is from the bus side to the terminal side. Data transfer is noninverting in both directions.

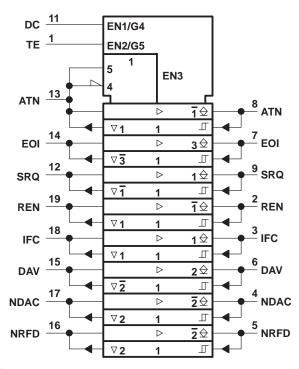
[†] ATN is a normal transceiver channel that functions additionally as an internal direction control or talk enable for EOI whenever the DC and TE inputs are in the same state. When DC and TE are in opposite states, the ATN channel functions as an independent transceiver only.



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	CHANNEL-IDENTIFICATION TABLE								
NAME	IDENTITY	CLASS							
DC	Direction Control								
TE	Talk Enable	Control							
SC	System Control (SN75162B only)								
ATN	Attention								
SRQ	Service Request								
REN	Remote Enable	Bus							
IFC	Interface Clear	Management							
EOI	End of Identity								
DAV	Data Valid								
NDAC	Not Data Accepted	Data							
NRFD	Not Ready for Data	Transfer							

SN75161B logic symbol[†]

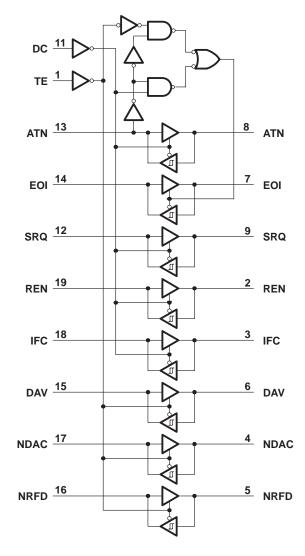


[†]This symbol is in accordance with IEEE Std 91-1984 and IEC Publication 617-12.

▽ Designates 3-state outputs

☆ Designates passive-pullup outputs

SN75161B logic diagram (positive logic)

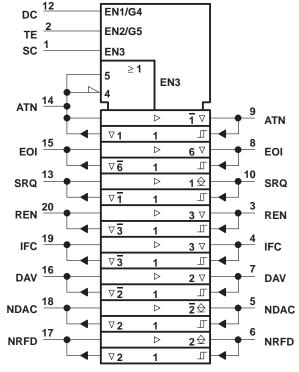




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SN75162B logic symbol[†]

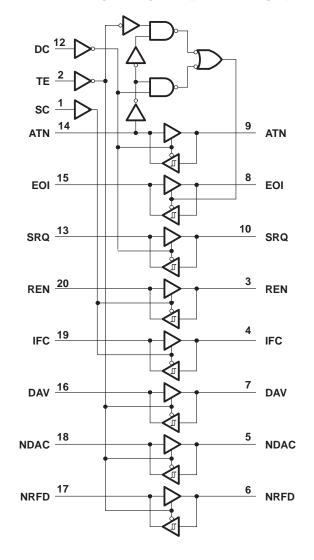
SN75162B logic diagram (positive logic)



[†]This symbol is in accordance with IEEE Std 91-1984 and IEC Publication 617-12.

▽ Designates 3-state outputs

O Designates passive-pullup outputs

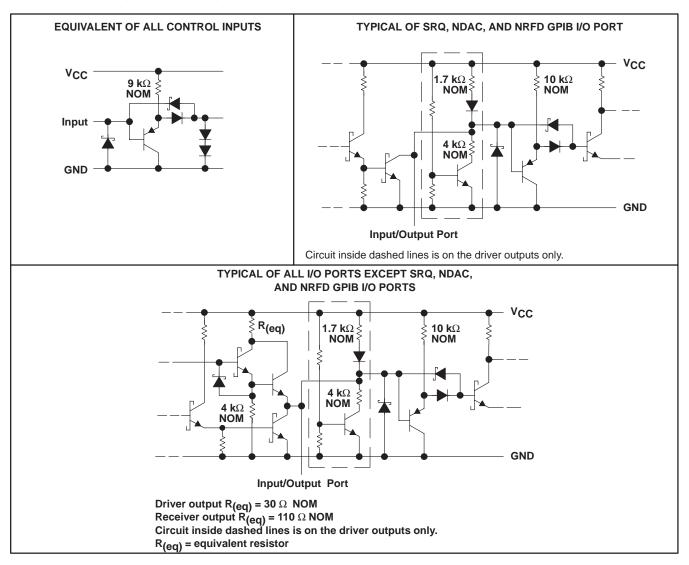


Pin numbers shown are for the N package.



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schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} (see Note 1)	
Input voltage, V _I	
Low-level driver output current, I _{OL}	100 mA
Continuous total power dissipation	. See Dissipation Rating Table
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16) inch from the case for 10 seconds	260°C

 Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
 NOTE 1: All voltage values are with respect to network ground terminal.



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DISSIPATION RATING TABLE									
PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING						
DW (20 pin)	1125 mW	9.0 mW/°C	720 mW						
DW (24 pin)	1350 mW	10.8 mW/°C	864 mW						
N (20 pin)	1150 mW	9.2 mW/°C	736 mW						
N (22 pin)	1700 mW	13.6 mW/°C	1088 mW						

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.75	5	5.25	V
High-level input voltage, VIH	2			V	
Low-level input voltage, VIL			0.8	V	
High lovel output ourrent love	Bus ports with 3-state outputs			-5.2	mA
	h-level output current, I _{OH} Bus ports with 3-state outputs Terminal ports			-800	μA
	Bus ports			48	A
Low-level output current, IOL	Terminal ports			16	mA
Operating free-air temperature, TA	0		70	°C	



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electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER		TES	T CONDITIONS	MIN	TYP [†]	MAX	UNIT
VIK	Input clamp voltage	-	l _l = – 18 mA			-0.8	-1.5	V
V _{hys}	Hysteresis voltage (V _{IT+} – V _{IT} _)	Bus	See Figure 7		0.4	0.65		V
Vaut	High-level output voltage	Terminal	I _{OH} = -800 μA	2.7	3.5		V	
VOH‡	nigh-level output voltage	Bus	$I_{OH} = -5.2 \text{ mA}$		2.5	3.3		v
VOL	Low-level output voltage	Terminal I _{OL} = 16 mA				0.3	0.5	v
VOL	OL Low-level output voltage		I _{OL} = 48 mA			0.35	0.5	v
łı	Input current at maximum input voltage	Terminal	VI = 5.5 V			0.2	100	μA
lιΗ	High-level input current	Terminal and	V _I = 2.7 V			0.1	20	μΑ
Ι _{ΙL}	Low-level input current	control inputs	$V_{I} = 0.5 V$			-10	-100	μΑ
M	Voltage at bus port		Driver disabled	$I_{I(bus)} = 0$	2.5	3.0	3.7	V
VI/O(bus)	voltage at bus port	-	Driver disabled	$I_{I(bus)} = -12 \text{ mA}$			-1.5	v
		Power on		$V_{I(bus)} = -1.5 V \text{ to } 0.4 V$	-1.3			
				V _{I(bus)} = 0.4 V to 2.5 V	0		-3.2	
			Driver disabled	$\sqrt{10}$ $\rightarrow 25 \sqrt{1027}$			2.5	mA
II/O(bus)	Current into bus port	Foweron	Driver disabled	VI(bus) = 2.5 V to 3.7 V			-3.2	-3.2
				V _{I(bus)} = 3.7 V to 5 V	0		2.5	
				$V_{I(bus)} = 5 V \text{ to } 5.5 V$	0.7		2.5	
		Power off	$V_{CC} = 0,$	$V_{I(bus)} = 0 V \text{ to } 2.5 V$			-40	μΑ
	Short-circuit output current	Terminal			-15	-35	-75	mA
IOS	Short-circuit output current	Bus			-25	-50	-125	IIIA
ICC	Supply current		No load,	TE, DE, and SC low			110	mA
C _{I/O(bus)}	Bus-port capacitance		V _{CC} = 5 V to 0, V _{I/O} = 0 to 2 V, f = 1 MHz			16		pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. [‡] V_{OH} applies for 3-state outputs only.



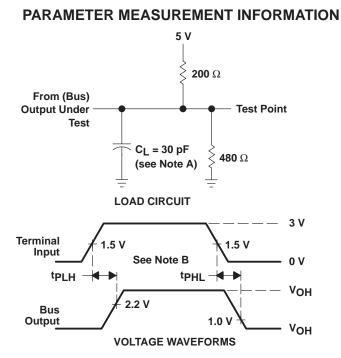
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switching characteristics, V_{CC} = 5 V, C_L = 15 pF, T_A = 25°C (unless otherwise noted)

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	МАХ	UNIT	
^t PLH	Propagation delay time, low- to high-level output	Terminal	Bus	C _L = 30 pF,		14		ns	
^t PHL	Propagation delay time, high- to low-level output	Terminar	Dus	See Figure 1		14	20	115	
^t PLH	Propagation delay time, low- to high-level output	Terminal	Bus (SRQ, NDAC, NRFD)	C _L = 30 pF, See Figure 1		29	35	ns	
^t PLH	Propagation delay time, low- to high-level output	Bus	Terminal	C _L = 30 pF,		10	20	ns	
^t PHL	Propagation delay time, high- to low-level output	Dus	Terminal	See Figure 2		15	22	115	
^t PZH	Output enable time to high level		Bus (ATN,				60		
^t PHZ	Output disable time from high level	TE,DC,	EOI, REN,	See Figure 3			45	20	
tPZL	Output enable time to low level	or SC	IFC, and	See Figure 5			60	ns	
^t PLZ	Output disable time from low level		DAV)				55		
^t PZH	Output enable time to high level						55		
^t PHZ	Output disable time from high level	TE,DC,	Terminal	See Figure 4			50		
t _{PZL}	Output enable time to low level	SC	reminal	See Figure 4			45	ns	
^t PLZ	Output disable time from low level						55		

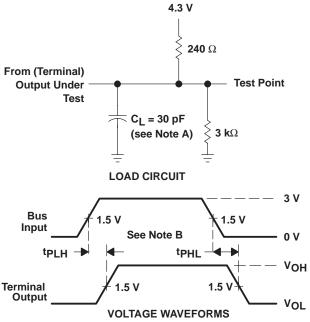


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- NOTES: A. CL includes probe and jig capacitance.
 - B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .

Figure 1. Terminal-to-Bus Load Circuit and Voltage Waveforms

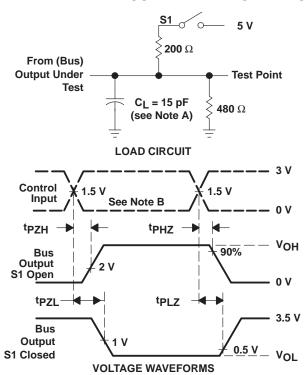


- NOTES: A. CL includes probe and jig capacitance.
 - B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .





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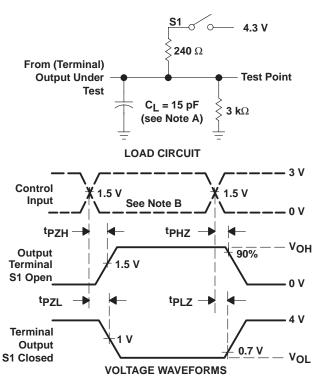
PARAMETER MEASUREMENT INFORMATION

- NOTES: A. $\ensuremath{\mathsf{C}}_L$ includes probe and jig capacitance.
 - B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .

Figure 3. Bus Enable and Disable Times Load Circuit and Voltage Waveforms



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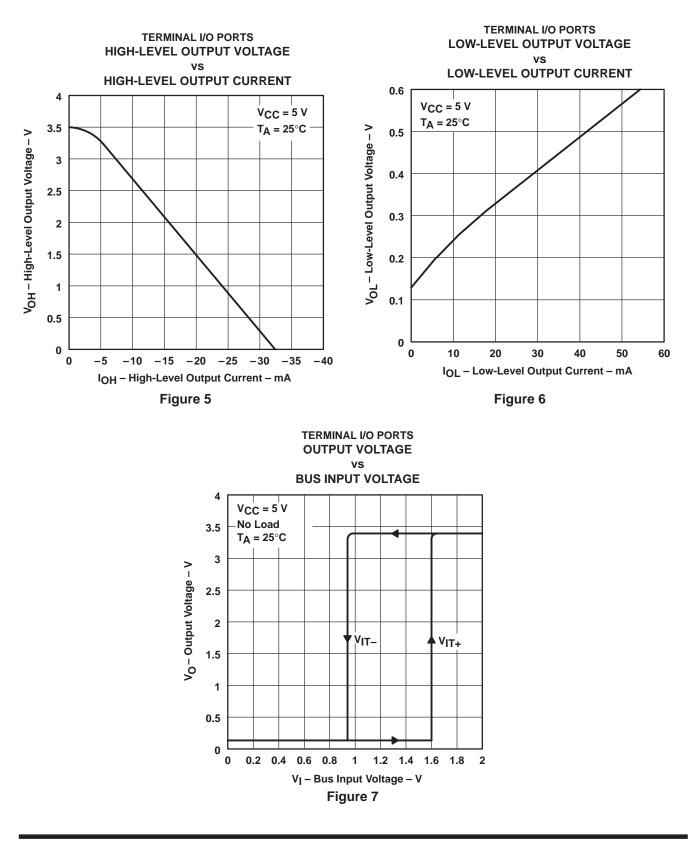
PARAMETER MEASUREMENT INFORMATION

- NOTES: A. CL includes probe and jig capacitance.
 - B. The Input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_f \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50 \Omega$.

Figure 4. Terminal Enable and Disable Times Load Circuit and Voltage Waveforms



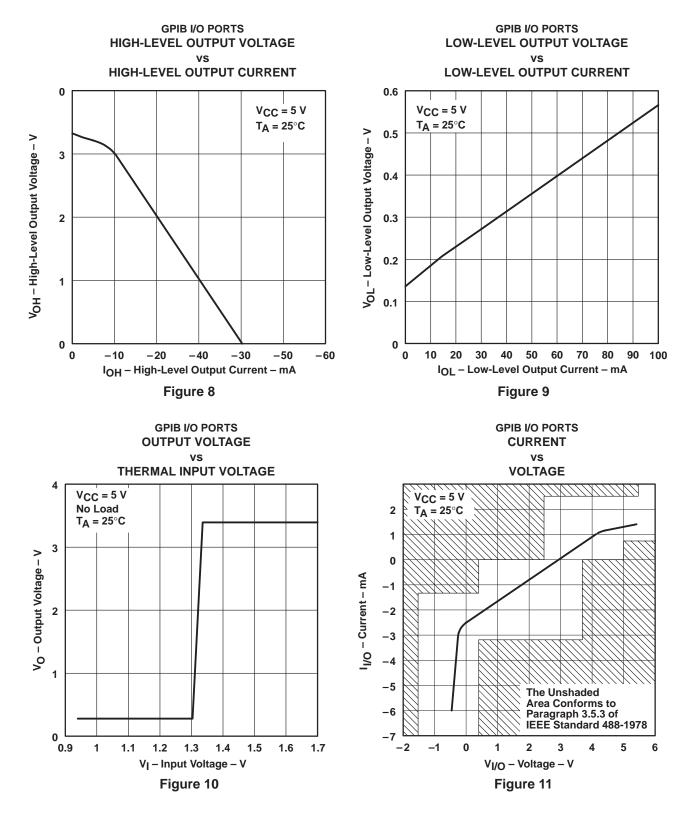
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TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75161BDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75161BDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75161BDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75161BDWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75161BDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75161BN	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75161BNE4	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75162BDW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75162BDWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75162BDWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75162BDWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75162BDWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75162BDWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75162BN	OBSOLETE	PDIP	Ν	22		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM



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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75161BDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN75161BDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN75162BDWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

3-Jan-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75161BDWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN75161BDWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN75162BDWR	SOIC	DW	24	2000	367.0	367.0	45.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



LAND PATTERN DATA



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



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